



Integrated Photonics for AI Datacenters

Pascal Langlois
co-founder & Chairman of the board

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Veteran team of industry experts



Mat
Crowley

CEO
2 X founder
Lead startups
to volume



Sylvie
Menezo

Founder s CTO
Tech visionary
Thought leader



Olivier
Potavin

COO
Implement
high volume
manufacturing



Jim
Theodoras

VP Product
Complete
product
delivery



Yannick
Paillard

VP Mktg/BD
Marketing, biz
dev, key
accounts



Pascal Langlois co-Founder & Chairman of the board

Powering optical networks in AI Datacenters

2

Partnerships with AI processor leaders

100+

SCINTIL owned patents or licensed by



10M

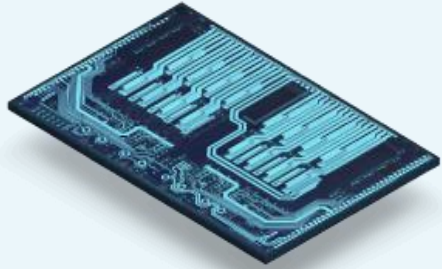
Units capacity per year

€73M

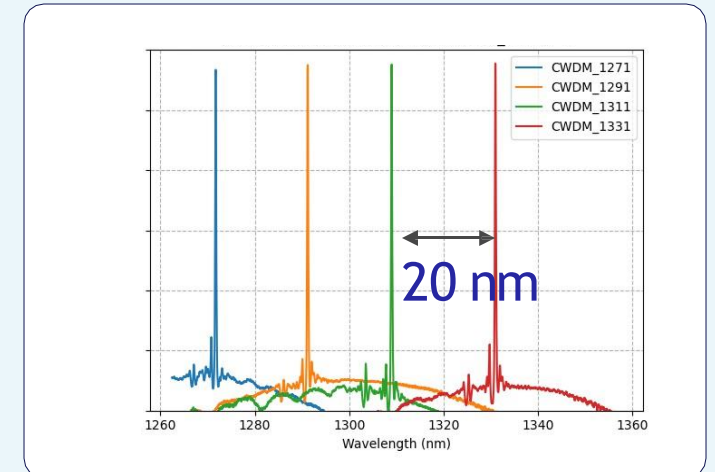
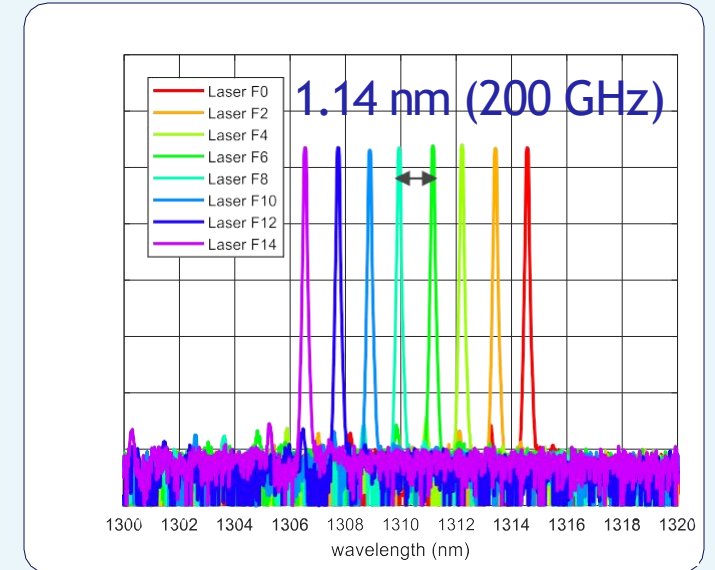
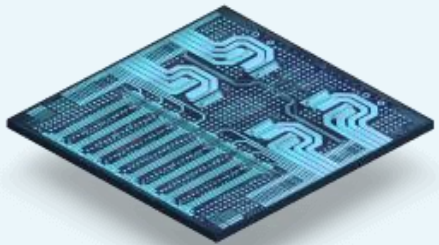
VC funding



SCINTIL Heterogeneous Integrated PICs



- 4-32 DWDM DFB lasers
- On-chip Mux's and DMux's: MZI and AWG
- CWDM or DWDM channel spacings
- Ge High Speed and Monitoring PDs
- Silicon MZM Modulators
- SiN edge couplers



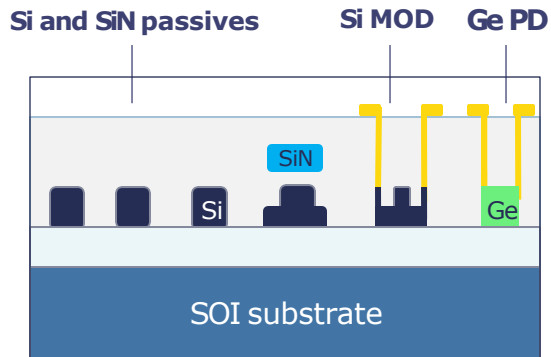
SHIP™ Process Explained

Standard SiPho

SCINTIL IP: laser integration on standard Si Photonics

1

Begin with standard silicon photonic wafer



Start with standard silicon photonics

2

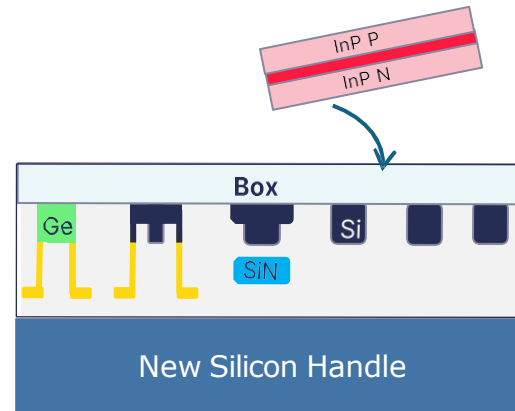
Handle exchange and remove the original SOI substrate



Buried Oxide Layer (BOX) Is exposed for bonding

3

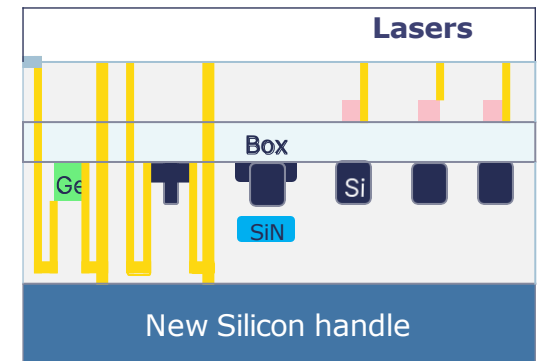
Bond of III-V material



Bond non patterned III-V die where lasers will be located
Laser wavelength is precisely controlled with photolithography

4

Fabricate lasers at the wafer level



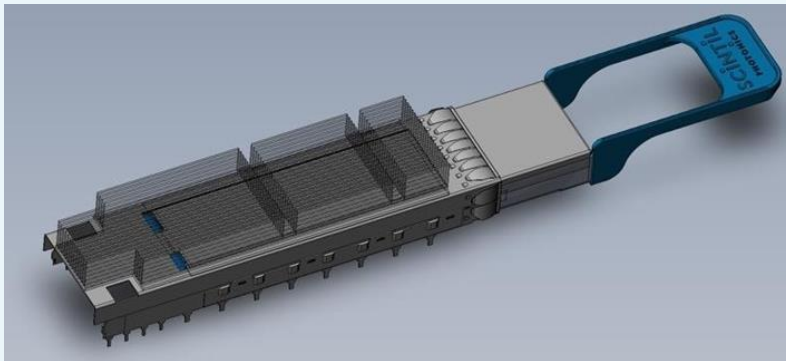
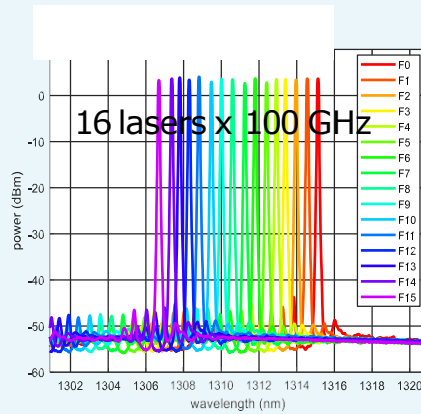
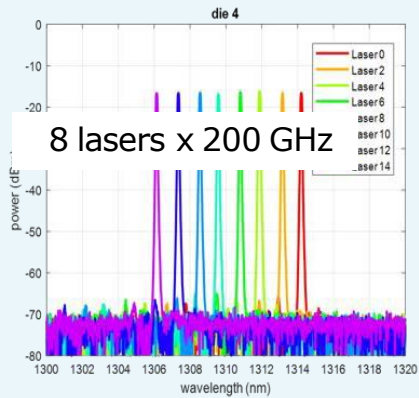
The III-V die are patterned to form the lasers, at the wafer level

Why customers choose Scintil

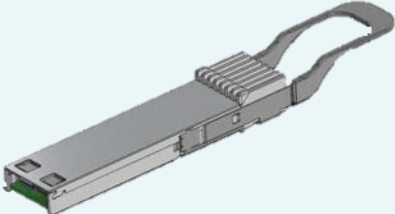
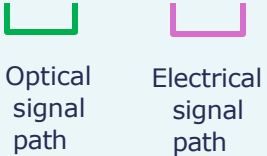
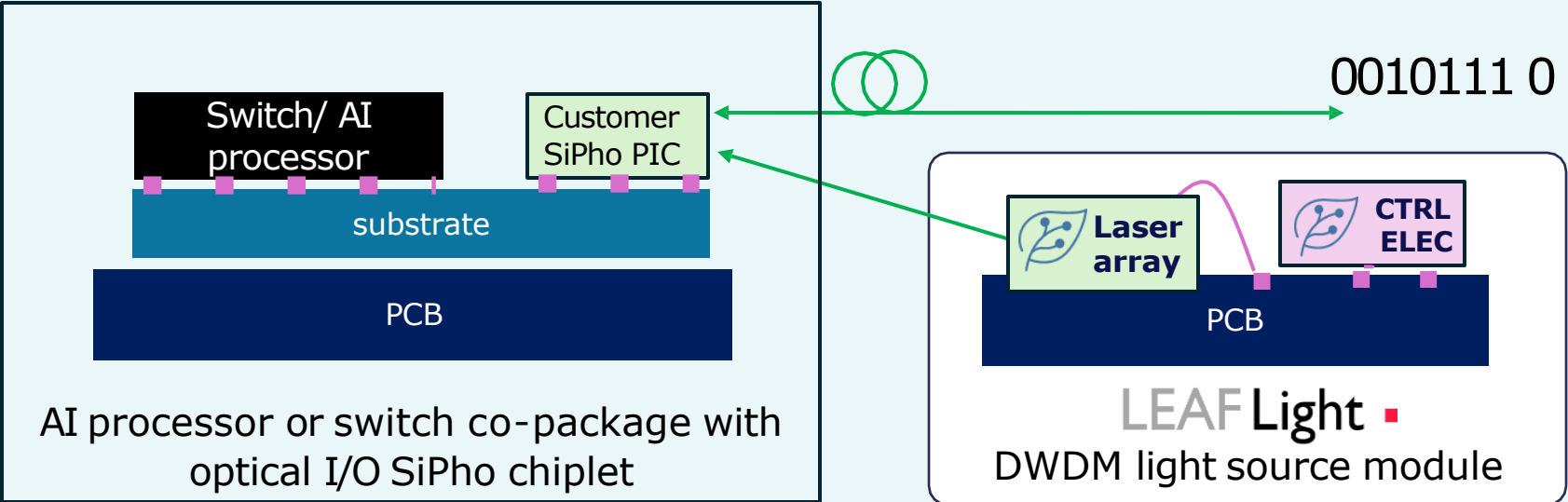
Scintil is the only company that has sampled light sources with all of the performance and features needed for DWDM systems

Scintil DFB lasers

- Finest, most accurate frequency spacing in the industry, 100 GHz
 - Critical for DWDM implementation
- Improved reliability (no Anti Reflective coatings required)
- Stable: No mode hops which can cause total loss of signal
- Wall Plug Efficiency up to 25% on chip
- Available power at 70°C > 20 mW

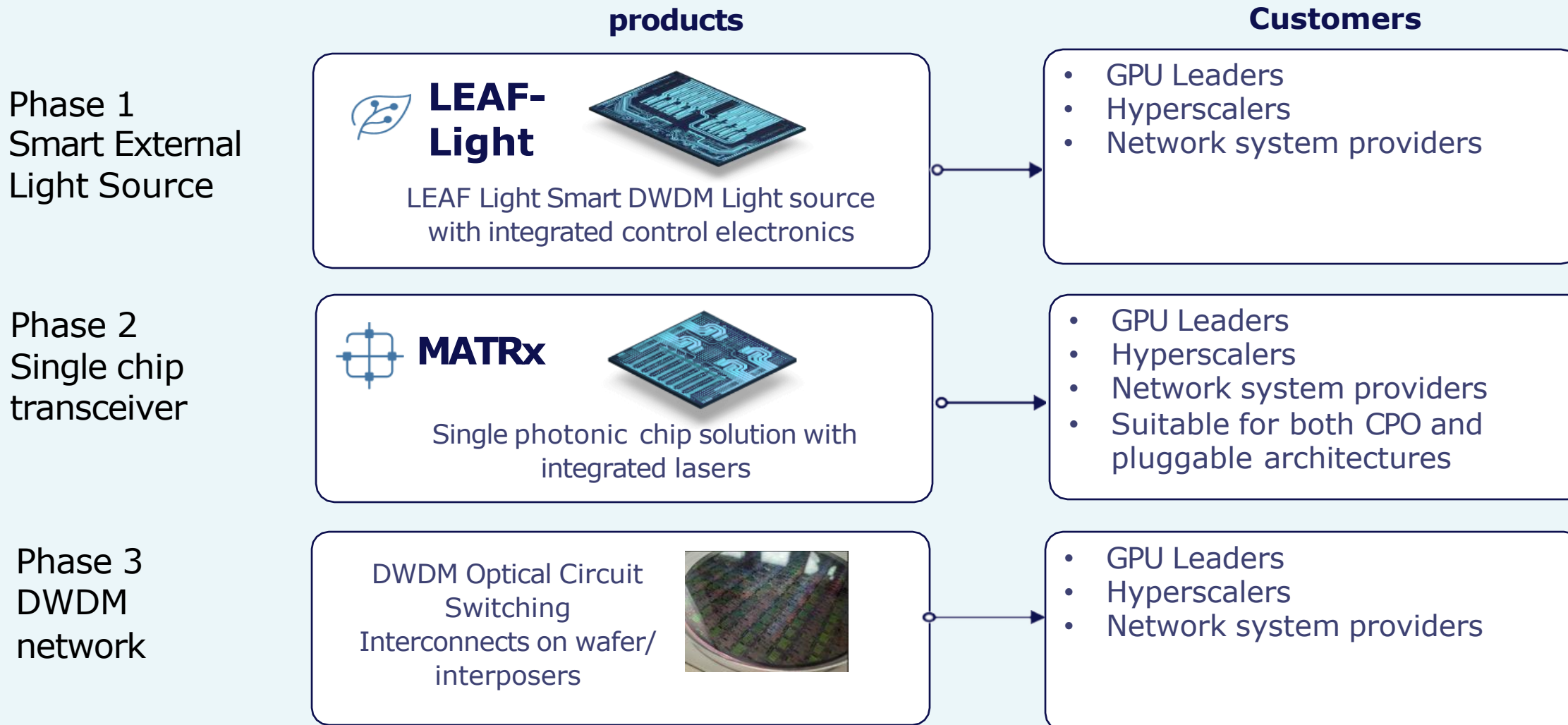


LEAF Light ■ Enabling dense and low power optical I/O



LEAF Light is the first **integrated** DFB laser array, compliant with DWDM specifications, and fabricated with Scintil Heterogeneous Integrated Photonics SHIP™ process

Leveraging the SHIP platform to create an optical network on a chip





Join the revolution in process[ing]

